



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	TLS810B1EJ V33	<b>Issued</b>	16. April 2021
<b>MA#</b>	MA005421211		
<b>Package</b>	PG-DSO-8-52	<b>Weight*</b>	83.68 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	1.19	1.19	11902	11902
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8696	
	non noble metal	copper	7440-50-8	29.548	35.31	36.23	353107	362347
wire	non noble metal	copper	7440-50-8	0.046	0.05	0.05	546	546
encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1207	
	plastics	epoxy resin	-	4.647	5.55		55530	
	inorganic material	silicondioxide	60676-86-0	45.760	54.69	60.36	546850	603587
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8307	8307
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8658	8658
glue	plastics	epoxy resin	-	0.097	0.12		1163	
	noble metal	silver	7440-22-4	0.292	0.35	0.47	3490	4653
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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